Transient Voltage Suppressors – TVS

Ultra-low clamping and capacitance (ULC) type

Series/Type:  SD01005SL-ULC101
Ordering code:  B74111U0033M060
Date:  2021-08-06
Version:  2

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Features

- Bidirectional ESD protection of one high speed I/O line
- ESD protection to IEC 61000-4-2, $V_{ESD,max} = 15 \text{ kV}$
- Surge protection to IEC 61000-4-5, $I_{PP,max} = 7.0 \text{ A}$
- Very low clamping voltage: $V_{clamp} = 3.8 \text{ V}$ at $I_{LP} = 8 \text{ A}$
- Very low leakage current: $I_{leak} = 1 \text{ nA}$ at $3.3 \text{ V}$
- Low capacitance: $C = 0.48 \text{ pF}$ at $1 \text{ MHz}$
- Ultra-small chip scale package with a height of $0.10 \text{ mm}$

Applications

- High-speed interfaces in smartphones, laptops, tablets, wearables and network communication devices and other portable devices with tight space requirements
- USB
- HDMI
- Thunderbolt
- Firewire
- DVI
- DisplayPort
- S-ATA
- SWP / NFC
- Other high-speed interfaces

Schematics

<table>
<thead>
<tr>
<th>Pin</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>A1</td>
<td>I/O Pin</td>
</tr>
<tr>
<td>B1</td>
<td>GND</td>
</tr>
</tbody>
</table>

Due to the symmetrical configuration no marking information is needed.
A1 and B1 can be interchanged.
## Maximum ratings

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>DC working voltage I/O to GND</td>
<td>( V_{RWM,\text{max}} )</td>
<td>3.3</td>
<td>V</td>
</tr>
<tr>
<td>ESD robustness air &amp; contact discharge</td>
<td>( V_{ESD,\text{max}} )</td>
<td>15</td>
<td>kV</td>
</tr>
<tr>
<td>Surge (8/20 ( \mu )s) peak pulse current (acc. to IEC 61000-4-5 standard)</td>
<td>( I_{pp,\text{max}} )</td>
<td>7</td>
<td>A</td>
</tr>
<tr>
<td>Ambient temperature</td>
<td>( T_A )</td>
<td>-40 … +125</td>
<td>°C</td>
</tr>
</tbody>
</table>

## Characteristics (\( T_A = 25 \ ^\circ \text{C} \))

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Minimum</th>
<th>Typical</th>
<th>Maximum</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Breakdown voltage</td>
<td>( V_{BR} )</td>
<td>( I_{BR} = 1 \text{ mA}, \ I/O \text{ to GND} )</td>
<td>5.0</td>
<td>6.3</td>
<td>8.0</td>
<td>V</td>
</tr>
<tr>
<td>Leakage current</td>
<td>( I_{\text{leak}} )</td>
<td>( V_{RWM} = 3.3 \text{ V} )</td>
<td>0.001</td>
<td>0.05</td>
<td></td>
<td>( \mu \text{A} )</td>
</tr>
<tr>
<td>Capacitance</td>
<td>( C )</td>
<td>( f = 1 \text{ MHz}, \ V_{DC,\text{bias}} = 0 \text{ V} )</td>
<td>0.48</td>
<td></td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Clamping voltage</td>
<td>( V_{\text{clamp}} )</td>
<td>( I_{\text{TLP}} = 8 \text{ A}, \ TLP \ 100\text{ns} )</td>
<td>3.8</td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Dynamic resistance</td>
<td>( R_{\text{dyn}} )</td>
<td>( I_{\text{TLP}} \text{ range: 8 ... 16 A, TLP} )</td>
<td>0.15</td>
<td></td>
<td></td>
<td>( \Omega )</td>
</tr>
</tbody>
</table>

**Note:** Any operating voltage lower than \( V_{RWM} \) results in lower leakage current.
Typical I-V characteristics

Typical I-V characteristics at triggering region
USB 3.2 Gen.2 eye diagram (10 Gbps per line, signal frequency 5 GHz)

with device

without device (test board reference)

Complete certified USB 3.2 Gen.2 compliance test report available upon request.
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**SD01005SL-ULC101**

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**Dimensional drawing**

![Dimensional drawing](image)

**Table: WL-CSP01005 SL**

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Mean</th>
<th>Tol.</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>0.40</td>
<td>±0.020</td>
</tr>
<tr>
<td>B</td>
<td>0.20</td>
<td>±0.020</td>
</tr>
<tr>
<td>T</td>
<td>0.10</td>
<td>±0.010</td>
</tr>
<tr>
<td>C</td>
<td>0.15</td>
<td>±0.020</td>
</tr>
<tr>
<td>D</td>
<td>0.10</td>
<td>±0.020</td>
</tr>
<tr>
<td>E</td>
<td>0.15</td>
<td>(typical)</td>
</tr>
<tr>
<td>e</td>
<td>0.25</td>
<td>(typical)</td>
</tr>
<tr>
<td>f</td>
<td>0.025</td>
<td>(typical)</td>
</tr>
</tbody>
</table>

Dimensions in mm

**Solder pad finish:** Ni / Au

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**Recommended reflow soldering footprint**

![Recommended footprint](image)

**Table: WL-CSP01005 SL**

<table>
<thead>
<tr>
<th>Footprint dimensions</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
</tr>
<tr>
<td>B</td>
</tr>
<tr>
<td>C</td>
</tr>
</tbody>
</table>

Dimensions in mm
Recommended soldering profiles

Reflow soldering

Temperature ranges for reflow soldering acc. to IEC 60068-2-58 recommendations.

![Diagram showing recommended soldering profile](image)

- **Max. ramp up rate = 3 °C/s**
- **Max. ramp down rate = 6 °C/s**

**T_p**

**T_L**

**T_{max}**

**T_{min}**

**T_{25°C}**

**T_{peak}**

- **t_p**
- **t_L**
- **t_s**

Time 25 °C to peak

TNT0880-P-E
### Profile feature

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Sn-Pb eutectic assembly</th>
<th>Pb-free assembly</th>
</tr>
</thead>
<tbody>
<tr>
<td>Preheat and soak</td>
<td></td>
<td></td>
</tr>
<tr>
<td>– Temperature min.</td>
<td>T_{smin}</td>
<td>100 °C</td>
</tr>
<tr>
<td>– Temperature max.</td>
<td>T_{smax}</td>
<td>150 °C</td>
</tr>
<tr>
<td>– Time</td>
<td>t_{smin} to t_{smax}</td>
<td>60 ... 120 s</td>
</tr>
<tr>
<td>Average ramp-up rate</td>
<td>T_{smax} to T_p</td>
<td>3 °C/s max.</td>
</tr>
<tr>
<td>Liquidous temperature</td>
<td>T_L</td>
<td>183 °C</td>
</tr>
<tr>
<td>Time at liquidous</td>
<td>t_L</td>
<td>40 ... 150 s</td>
</tr>
<tr>
<td>Peak package body temperature</td>
<td>T_p (^{1)})</td>
<td>215 ... 260 °C</td>
</tr>
<tr>
<td>Time (t_p) above (T_p -5 °C )</td>
<td>t_p</td>
<td>10 ... 40 s</td>
</tr>
<tr>
<td>Average ramp-down rate</td>
<td>T_p to T_{smax}</td>
<td>6 °C/s max.</td>
</tr>
<tr>
<td>Time 25 °C to peak temperature</td>
<td></td>
<td>maximum 8 min</td>
</tr>
</tbody>
</table>

\(^{1)}\) Depending on package thickness

**Note:** All temperatures refer to topside of the package, measured on the package body surface.

Number of reflow cycles: 3

Iron soldering should be avoided, hot air methods are recommended for repair purposes.

### Soldering guidelines

**Recommended solder**

The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.
Taping and packaging

- Tape and reel packing according to IEC 60286-3
- Tape material: Cardboard
- Component pitch in tape: 2 mm

Dimensions and tolerances

<table>
<thead>
<tr>
<th>Definition</th>
<th>Symbol</th>
<th>Dimension</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Tape width</td>
<td>W</td>
<td>8.0</td>
<td>±0.3</td>
</tr>
</tbody>
</table>

- Package: 8-mm tape
- Packing material: Plastic

Reel dimensions

<table>
<thead>
<tr>
<th>Definition</th>
<th>Symbol</th>
<th>Dimension</th>
<th>Tolerance</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reel diameter</td>
<td>A</td>
<td>180</td>
<td>+0/-3</td>
</tr>
<tr>
<td>Reel width (inside)</td>
<td>W₁</td>
<td>8.4</td>
<td>+1.5/-0</td>
</tr>
<tr>
<td>Reel width (outside)</td>
<td>W₂</td>
<td>14.4</td>
<td>max.</td>
</tr>
</tbody>
</table>

Packing unit: 20 000 pcs./reel
Cautions and warnings

General

Some parts of this publication contain statements about the suitability of our transient voltage suppressor (TVS) for certain areas of application, including recommendations about incorporation/design-in of these products into customer applications. The statements are based on our knowledge of typical requirements often made of our TVS devices in the particular areas. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our TVS components for a particular customer application. As a rule, TDK Electronics is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always incumbent on the customer to check and decide whether the TVS devices with the properties described in the product specification are suitable for use in a particular customer application.

- Do not use TDK Electronics TVS components for purposes not identified in our specifications, application notes and data books.
- Ensure the suitability of a TVS in particular by testing it for reliability during design-in. Always evaluate a TVS component under worst-case conditions.
- Pay special attention to the reliability of TVS devices intended for use in safety-critical applications (e.g. medical equipment, automotive, spacecraft, nuclear power plant).

Design notes

- Always connect a TVS in parallel with the electronic circuit to be protected.
- Consider maximum rated power dissipation if a TVS has insufficient time to cool down between a number of pulses occurring within a specified isolated time period. Ensure that electrical characteristics do not degrade.
- Consider derating at higher operating temperatures. Choose the highest voltage class compatible with derating at higher temperatures.
- Surge currents beyond specified values will puncture a TVS. In extreme cases a TVS will burst.
- If steep surge current edges are to be expected, make sure your design is as low-inductance as possible.
- In some cases the malfunctioning of TVS components or failure before the end of their service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In applications requiring a very high level of operational safety and especially when the malfunction or failure of a passive electronic component could endanger human life or health (e.g. in accident prevention, life-saving systems, or automotive battery line applications such as clamp 30), ensure by suitable design of the application or other measures (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of such a malfunction or failure.
- Specified values only apply to TVS components that have not been subject to prior electrical, mechanical or thermal damage. The use of TVS devices in line-to-ground applications is therefore not advisable, and it is only allowed together with safety countermeasures like thermal fuses.
Storage

- Only store TVS in their original packaging. Do not open the package before storage.
- Storage conditions in original packaging: temperature −25 to +45°C, relative humidity ≤75% annual average, maximum 95%, dew precipitation is inadmissible.
- Do not store TVS devices where they are exposed to heat or direct sunlight. Otherwise the packaging material may be deformed or TVS may stick together, causing problems during mounting.
- Avoid contamination of the TVS surface during storage, handling and processing.
- Avoid storing TVS devices in harmful environments where they are exposed to corrosive gases for example (SOx, Cl).
- Use TVS as soon as possible after opening factory seals such as polyvinyl-sealed packages.
- Solder TVS components after shipment from TDK Electronics within the time specified:
  - TVS with Ni/Au termination, 12 months

Handling

- Do not drop TVS components and allow them to be chipped.
- Do not touch TVS with your bare hands - gloves are recommended.
- Avoid contamination of the TVS surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

Mounting

- When TVS devices are encapsulated with sealing material or overmolded with plastic material, electrical characteristics might be degraded and the life time reduced.
- Make sure an electrode is not scratched before, during or after the mounting process.
- Make sure contacts and housings used for assembly with TVS components are clean before mounting.
- The surface temperature of an operating TVS can be higher. Ensure that adjacent components are placed at a sufficient distance from a TVS to allow proper cooling.
- Avoid contamination of the TVS surface during processing.

Soldering

- Complete removal of flux is recommended to avoid surface contamination that can result in an instable and/or high leakage current.
- Use resin-type or non-activated flux.
- Bear in mind that insufficient preheating may cause cracks.
- Rapid cooling by dipping in solvent is not recommended, otherwise a component may crack.
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